



PATENT 0171-0829P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Kazuhiro WATAYA et al. Conf.: 1264

Appl. No.: 10/092,503 Group: 1773

Filed: March 8, 2002 Examiner: S. Ahmed

For: THERMAL SPRAY SPHERICAL PARTICLES, AND

SPRAYED COMPONENTS

LARGE ENTITY TRANSMITTAL FORM

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

August 13, 2004

Sir:

Transmitted herewith is an amendment in the above-identified application.

Ш	The enclose	ed document	is	being	transmitted	l via	the	Certificate
	of Mailing	provisions	of	37 C.	F.R. § 1.8	•		

The enclosed document is being transmitted via facsimile.

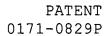
The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR		PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	15	_	- 20		0	\$ 18	\$0.00
INDEPENDENT 2		_	3	=	0	\$ 86	\$0.00
☐ FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM \$290 \$0.0							\$0.00
						TOTAL	\$0.00

(Rev. 02/08/2004)

	· · ·	(s) extension of time pursuant to $S(a)$. $\$0.00$ for the extension of					
\boxtimes	No fee is required.	•					
	Check(s) in the amount of \$0.00 is(are) enclosed.						
	Please charge Deposit Accou \$0.00. This form is submitted	ant No. $02-2448$ in the amount of ed in triplicate.					
overprequ:	current, and future replies, rpayment to Deposit Account No	ner is hereby authorized in this, to charge payment or credit any o. 02-2448 for any additional fees 16 or under 37 C.F.R. § 1.17; fees.					
	Resp	ectfully submitted,					
	BIRG	H, STEWART, KOLASCH & BIRCH, LLP					
•	/RG/csm Fall	Box 747 .s Church, VA/22040-0747 .) 205-8000					

Attachment(s)





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REPLY UNDER 37 C.F.R. § 1.111

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

August 13, 2004

Sir:

In reply to the Office Action dated May 18, 2004, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes Amendmnets to the Specification and Remarks.